

CHEMTRONICS®

Technical Data Sheet

TDS # SWNC

Soder-Wick® No Clean Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® No Clean is designed to provide fast and safe desoldering without leaving behind flux residues. Soder-Wick® No Clean uses an extremely pure, oxygen free copper braid to make a system that optimizes heat transfer to the solder joint. It is coated with a patented low solids organic “No Clean” flux. Soder-Wick® No Clean is provided in an ESD safe package for protection against damage due to static electricity.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized weave design for faster wicking and heat transfer
- Halide free
- ESD Safe packaging meets:
 - DOD Standard 1686
 - DOD Handbook 263
 - Static decay provision of MIL-B-81705C
- Minimal risk of heat and static component damage

TYPICAL APPLICATIONS

Soder-Wick® No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Surface Insulation Resistance			
Bellcore TR-NWT-000078		: PASS	
After 96 Hours (megohms) 2×10^4 Limit			
<u>Group A</u>	<u>Group B</u>	<u>Group C</u>	
4.8×10^6	3.8×10^6	4.1×10^6	
IPC SF-818		: PASS	
After 168 Hours (ohms) 1.8×10^8 Limit			
<u>1-2</u>	<u>2-3</u>	<u>3-4</u>	<u>4-5</u>
2.3×10^{10}	2.6×10^{10}	2.8×10^{10}	2.8×10^{10}
Electromigration		: PASS	
Average Insulation Resistance (megohms)-One Decade Limit			
	<u>Initial</u>	<u>Final</u>	
Group E	3.93×10^3	1.24×10^4	
Group F	3.87×10^3	2.84×10^4	
At 10x magnification no evidence of electromigration or heavy corrosion.			
Silver Chromate Test Paper		PASS	
Copper Mirror Test		PASS	

SODER-WICK® NO CLEAN IS DESIGNED TO MEET OR EXCEED:

MIL-F-14256F, Type R	MIL-STD-2000A
NASA NHB5300.4	NASA SP-5002
NASA NPC200-4	

AVAILABILITY

Part #	Size Inches	Color	Size Metric
1	.030"	White	.76mm
2	.060"	Yellow	1.52mm
3	.080"	Green	2.03mm
4	.110"	Blue	2.79mm
5	.145"	Brown	3.68mm
6	.210"	Red	5.33mm
BGA	-	Purple	-

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick[®] No Clean wick equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly smaller than the pad or connection.
- 3) Set temperature of iron between 600-750°F.
- 4) Place wick on solder joint and place tip of hot iron on top of wick.
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from joint simultaneously once color change has stopped.
- 7) The component lead is now clean and free from solder.
- 8) Clip and discard used portion of the wick.

TECHNICAL & APPLICATION ASSISTANCE

Chemtonics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

Part #	Size	Length	Part #	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

VacuPakTM Packaging

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

Part #	Size
SW16015	1
SW16025	2
SW16035	3
SW16045	4
SW16055	5

NOTE:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. Chemtronics® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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